

Heat Sink Paste | 1.0 g | Injection | 8 pcs

General information

Heat sink compound suitable for PCBs in transistors, for diodes, CPUs etc.

Use it between -50 °C and 180 °C

1 g compound injection type

8 injections per bag

Specifications

Content: 8 pcs

Packaging: Bag

Package contents

8x injection



Sales information

Order code: **HSPA01I**

Product description: Heat Sink Paste | 1.0 g | Injection | 8 pcs

Packaging: Polybag

Brand name: Nedis



Quantity	LxWxH (mm)			Weight
1	70 mm	15 mm	100 mm	23 g
8	70 mm	15 mm	100 mm	23 g
96	195 mm	65 mm	150 mm	273 g